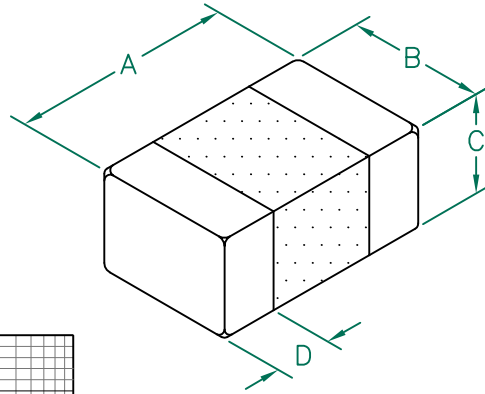


HI0805R800R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	± 0.20 [.008]
B	1.25 [.049]	± 0.20 [.008]
C	0.90 [.035]	± 0.20 [.008]
D	0.51 [.020]	± 0.25 [.010]



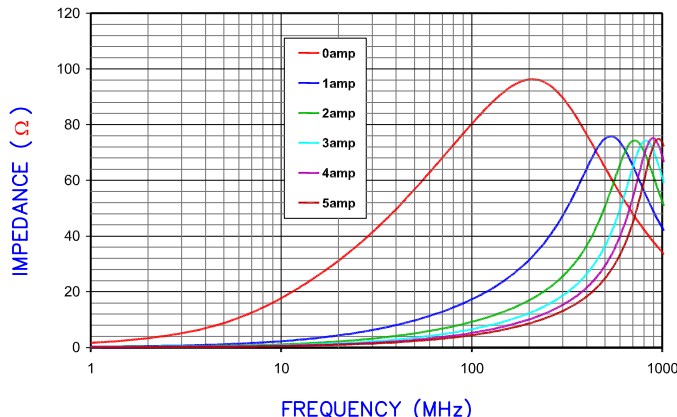
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	80	
Minimum	60	
Maximum	100	0.010
		5000 mA

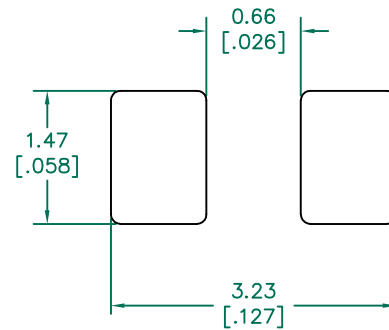
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REE, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. CONTINUOUS CURRENT RATING OF 5000 mA.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

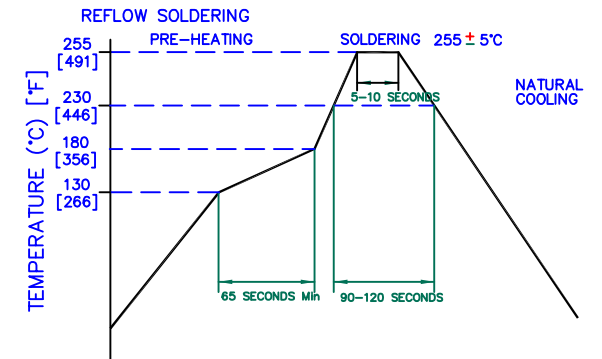


LAND PATTERNS FOR REFLOW SOLDERING

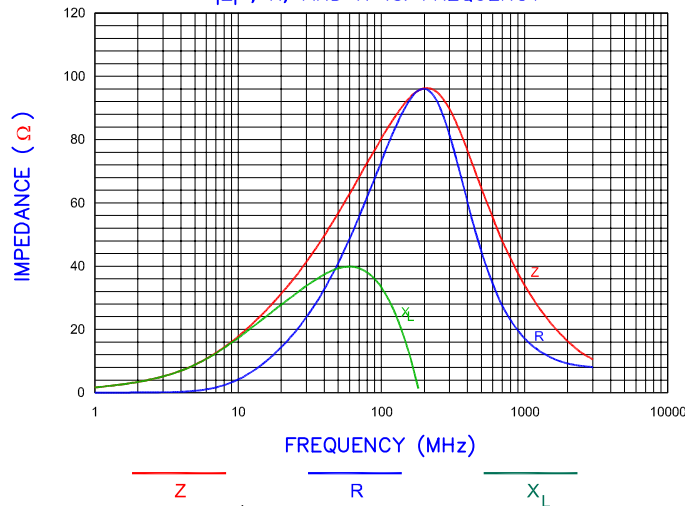


(For wave soldering, add 0.763 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



FREQUENCY (MHz)
|Z|, R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3796

DIMENSIONS ARE IN mm [INCHES].

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E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
D	CHANGE TO PAPER TAPE	03/03/10	JUN	HI0805R800R-10	E	CO-FIRE	TMB
C	UPDATE COMPANY LOGO	06/15/09	JRK	DATE:	SCALE:	NTS	SHEET:
B	UPDATE COMPANY LOGO	01/17/08	JRK	04/02/04			2 of 2
A	ORIGINAL DRAFT	04/02/04	TMB	CAD #	TOOL #	-	
REV	DESCRIPTION	DATE	INT	HI0805R800R-10-E			